Korean International Semiconductor Conference & Exhibition
on Manufacturing Technology 2025

KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[WeF2] Materials and Processing for Advanced Packaging

Session Date	November 12 (Wed.), 2025
Session Time	14:10-15:50
Session Room	Room F (Panorama Room, 16F)
Session Chair	Prof. Ah-Young Park (Univ. of Seoul, Korea)

[WeF2-1] [Invited] **14:10-14:30**

Development of an Eco-Friendly Photoresist Stripper for Advanced Semiconductor Packaging Processes

Bo Yeon Lee, Sangseung Park, Seungeun Lee, Ga Young Kim, Seok Jin Hong, and Jung Shik Heo (ENF Technology Co., Ltd., Korea)

[WeF2-2] [Invited] **14:30-14:50**

FINE Cut and FINE Forming (TGV) of HBM4, Glass Core and Interposer

Seak-Joon Lee (ITI, Korea)

[WeF2-3] [Invited] **14:50-15:10**

Glass Package Substrates for High-Performance Chiplet Systems

Jimin Kwon (UNIST, Korea)

[WeF2-4] [Invited] **15:10-15:30**

Bonding Strength and Fracture Behavior in Patterned Cu–SiO_2 Hybrid Interfaces

Ah-Young Park (Univ. of Seoul, Korea), Hakyung Jeong (KIMM, Korea), and Kyung-Ho Park (KANC, Korea)

[WeF2-5] [Invited] **15:30-15:50**

Development of Optical Interconnection Core Technologies for Implementation and Reliability Enhancement of Co-Packaged Optics

Hongyun So, Keuntae Baek, and Animesh Sinha (Hanyang Univ., Korea)